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SEK 18 male low profile solder and press-in RoHS compliant				Recommended configuration of plated through holes for press-in termination In addition to the hot-air-level (HAL), other PCB surfaces are getting more important. Due to their different properties – such as mechanical strength and coefficient of friction – we recommend the following configuration of PCB through holes. <table><tr><td rowspan="3">Tin plated PCB (HAL) acc. to EN 60352-5</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>plated hole Ø</td><td>0,94 – 1,09 mm</td></tr><tr><td rowspan="3">Chemical tin plated PCB</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Sn</td><td>min. 0,8µm</td></tr><tr><td></td><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td rowspan="5">Gold /Nickel plated PCB</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Ni</td><td>3 – 7 µm</td></tr><tr><td>Au</td><td>0,05 – 0,12 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td rowspan="3">Silver plated PCB</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>Ag</td><td>0,1 – 0,3 µm</td></tr><tr><td></td><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr><tr><td rowspan="3">Copper plated PCB (OSP)</td><td>Drilled hole Ø</td><td>1,15-0,03 mm</td></tr><tr><td>Cu</td><td>min. 25 µm</td></tr><tr><td>plated hole Ø</td><td>1,00 – 1,10 mm</td></tr></table>				Tin plated PCB (HAL) acc. to EN 60352-5	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	plated hole Ø	0,94 – 1,09 mm	Chemical tin plated PCB	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Sn	min. 0,8µm		plated hole Ø	1,00 – 1,10 mm	Gold /Nickel plated PCB	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Ni	3 – 7 µm	Au	0,05 – 0,12 µm	plated hole Ø	1,00 – 1,10 mm	Silver plated PCB	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	Ag	0,1 – 0,3 µm		plated hole Ø	1,00 – 1,10 mm	Copper plated PCB (OSP)	Drilled hole Ø	1,15-0,03 mm	Cu	min. 25 µm	plated hole Ø	1,00 – 1,10 mm																																															
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Derating diagram acc to IEC 60512-2 (Current carrying capacity) The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals. The current capacity-curve is valid for continuous, not interrupted current-loaded contacts of connectors when simultaneous power on all contacts is given without exceeding the maximum temperature. Control and test procedures according to DIN IEC 60512. 1) Temperature rise 2) Derating 3) Derating curve at I max x 0.8(IEC 60512-2)				All rights reserved Department EC PD – DE HARTING Electronics GmbH D-32339 Espelkamp All Dimensions in mm Original Size DIN A3 Scale 1:1 Free size tol. Created by STORCK Inspected by LEHNERT Standardisation HOFFMANN Date 2016-09-05 State Final Release Title SEK 18 male low profile solder and press-in Type DS Number 09181100001 Doc-Key / ECM-Nr. 100554984/UGD/001/F 500000107692 Rev. F Page 1/1																																																																																															
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